

TwinChip™ Series - DO-15



Agency Approvals

Agency	Agency File Number
	E133083

Pinout Designation

NOT APPLICABLE

Schematic Symbol



Description

TwinChip™ Series DO-15 are very low capacitance SIDACTor® thyristors are designed to protect broadband CPE equipment, such as VoIP and xDSL modems from damaging overvoltage transients. The series provides a through-hole solution that enables equipment to comply with global regulatory standards while limiting the impact to broadband signals.

Features & Benefits

- Differential protection
- Low insertion loss
- Low capacitance
- GDT compatible axial footprint
- Low voltage overshoot
- Does not degrade surge capability after multiple
- surge events within limit.
- Fails short circuit when surged in excess of ratings
- RoHS Compliant
- Pb-free E3 means 2nd level interconnect is Pb-free and the terminal finish material is tin(Sn) (IPC/JEDEC J-STD-609A.01)

Applicable Global Standards

- TIA-968-A
- TIA-968-B
- ITU K.20/21/45 Basic Level
- GR 1089 Intra-building
- IEC 61000-4-5 2nd edition
- YD/T 1082
- YD/T 993
- YD/T 950

Electrical Characteristics

Part Number	Marking	$V_{DRM} @ I_{DRM}=5\mu A$	$V_S @ 100V/\mu s$	I_H	I_S	I_T	$V_T @ I_T = 2.2 \text{ Amps}$	@ 1MHz @ 2V bias	
		V min	V max	mA min	mA max	A max	V max	pF min	pF max
P2602GBLRP	P262B	220	300	150	800	2.2	8	15	25
P3002GBLRP	P30B	280	360	150	800	2.2	8	10	20
P3502GBLRP	P352B	320	400	150	800	2.2	8	10	20
P4502GBLRP*	P452B	400	530	150	800	2.2	8	25	45

Notes:

- Absolute maximum ratings measured at $T_A = 25^\circ C$ (unless otherwise noted).
- Components are bi-directional.

Additional Information



Datasheet



Resources



Samples

Surge Ratings

Series	I_{PP}			I_{TSM}
	10/160 ¹ 10/160 ²	10/1000 ¹ 10/1000 ²	5/310 ¹ 10/700 ²	50 / 60 Hz
	A min	A min	A typ	A min
B	100	80	150	25

Notes:

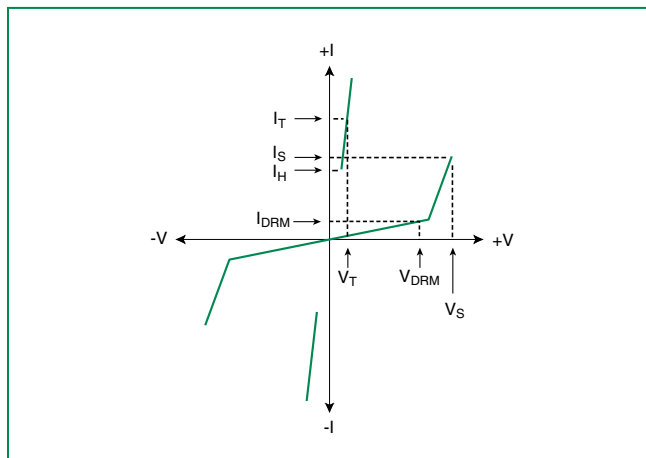
- 1 Current waveform in μs
2 Voltage waveform in μs

- Peak pulse current rating (I_{PP}) is repetitive and guaranteed for the life of the product that remains in thermal equilibrium.
- I_{PP} ratings applicable over temperature range of -40°C to +85°C
- The component must initially be in thermal equilibrium with -40°C $\leq T_J \leq$ +150°C

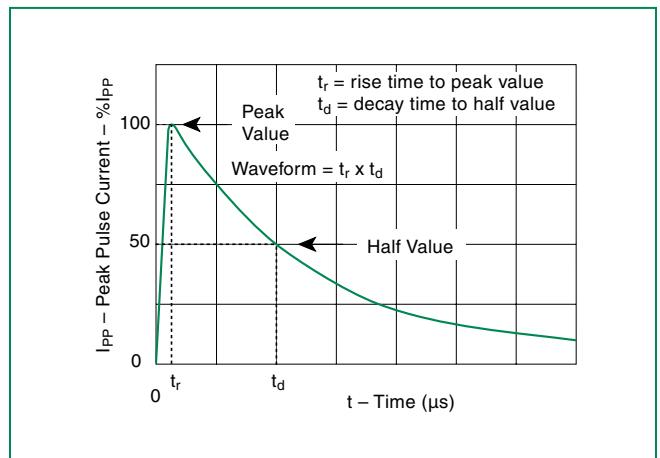
Thermal Considerations

Package	Symbol	Parameter	Value	Unit
 DO-15	T_J	Operating Junction Temperature Range	-40 to +150	°C
	T_S	Storage Temperature Range	-65 to +150	°C
	$R_{\theta JA}$	Thermal Resistance: Junction to Ambient	120	°C/W

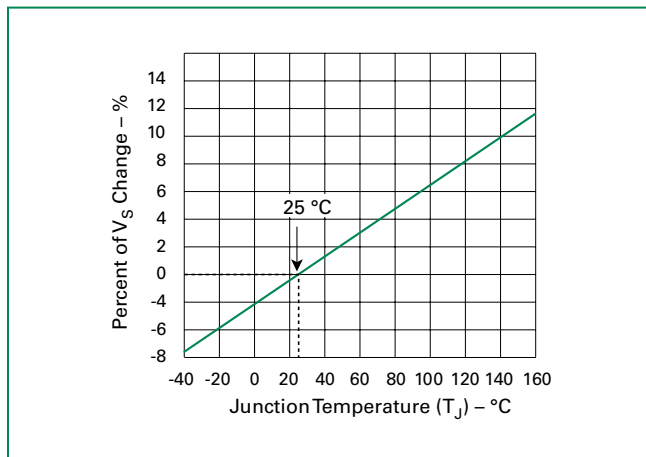
V-I Characteristics



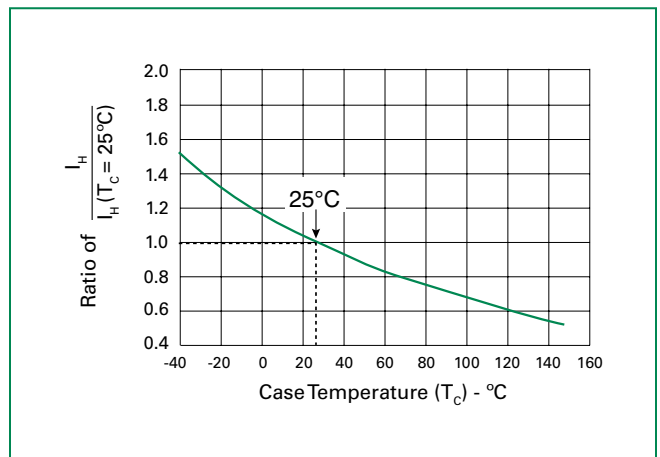
$t_r \times t_d$ Pulse Waveform



Normalized V_S Change vs. Junction Temperature

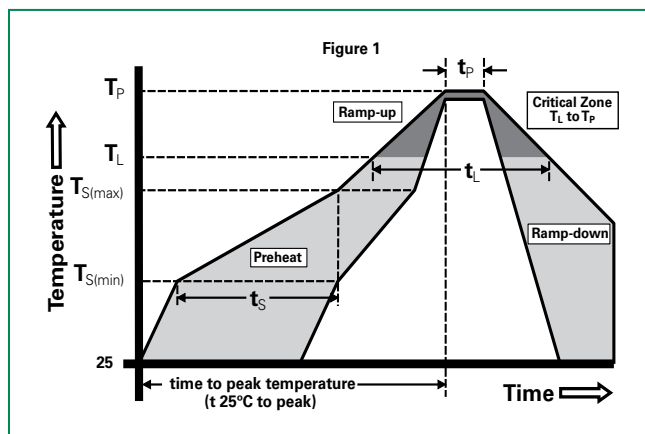


Normalized DC Holding Current vs. Case Temperature



Soldering Parameters

Reflow Condition		Pb-Free assembly (see Figure 1)
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60-180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60-150 seconds
Peak Temperature (T_p)		260(+0/-5)°C
Time within 5°C of actual peak Temperature (t_p)		30 seconds max
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes max
Do not exceed		260°C



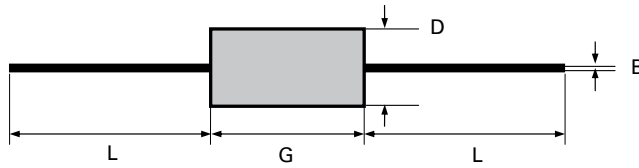
Physical Specifications

Lead Material	Copper Alloy
Terminal Finish	100% Matte-Tin Plated
Body Material	UL Recognized epoxy meeting flammability classification V-0

Environmental Specifications

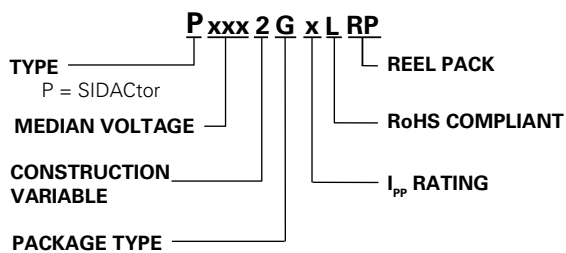
High Temp Voltage Blocking	80% Rated V_{DRM} (V_{AC} Peak) +125°C or +150°C, 504 or 1008 hrs. MIL-STD-750 (Method 1040) JEDEC, JESD22-A-101
Temp Cycling	-65°C to +150°C, 15 min. dwell, 10 up to 100 cycles. MIL-STD-750 (Method 1051) EIA/ JEDEC, JESD22-A-104
Biased Temp & Humidity	52 V_{DC} (+85°C) 85%RH, 504 up to 1008 hrs. EIA/JEDEC, JESD22-A-101
High Temp Storage	+150°C 1008 hrs. MIL-STD-750 (Method 1031) JEDEC, JESD22-A-101
Low Temp Storage	-65°C, 1008 hrs.
Thermal Shock	0°C to +100°C, 5 min. dwell, 10 sec. transfer, 10 cycles. MIL-STD-750 (Method 1056) JEDEC, JESD22-A-106
Autoclave (Pressure Cooker Test)	+121°C, 100%RH, 2atm, 24 up to 168 hrs. EIA/JEDEC, JESD22-A-102
Resistance to Solder Heat	+260°C, 30 secs. MIL-STD-750 (Method 2031)
Moisture Sensitivity Level	85%RH, +85°C, 168 hrs., 3 reflow cycles (+260°C peak). JEDEC-J-STD-020, Level 1

Dimensions — DO-15

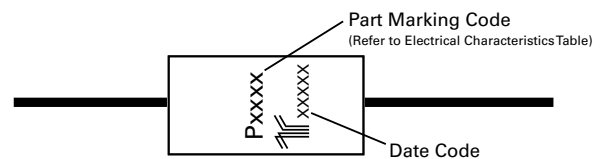


Dimension	Inches		Millimeters	
	min	max	min	max
B	0.028	0.034	0.711	0.864
D	0.12	0.14	3.048	3.556
G	0.235	0.27	5.969	6.858
L	1		25.4	

Part Numbering



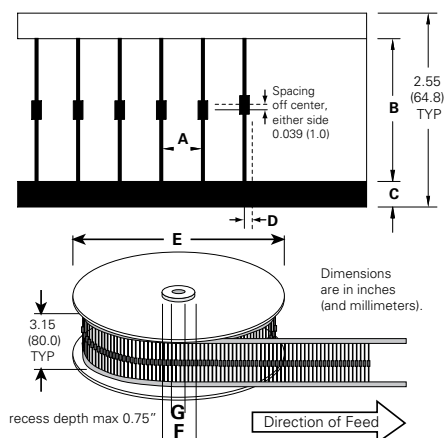
Part Marking



Packing Options

Package Type	Description	Quantity	Added Suffix	Industry Standard
G	DO-15 Axial Tape & Reel	5000	RP	EIA-RS-296-D

Tape and Reel Specification — DO-15



Symbols	Description	inch	mm
A	Component Spacing (lead to lead)	0.200 ± 0.020"	5.08 ± 0.508
B	Inner Tape Pitch	2.062 ± 0.059"	52.37 ± 1.498
C	Tape Width	0.250"	6.35
D	Max. Off Alignment	0.048"	1.219
E	Reel Dimension	13"	330.2
F	Max. Hub Recess	3"	76.19
G	Max. Arbor Hole	0.68"	17.27

Disclaimer Notice - Information furnished is believed to be accurate and reliable. However, users should independently evaluate the suitability of and test each product selected for their own applications. Littelfuse products are not designed for, and may not be used in, all applications. Read complete Disclaimer Notice at www.littelfuse.com/disclaimer-electronics.